

2SK3446

Silicon N Channel Power MOS FET Power Switching

REJ03G1100-0800 (Previous: ADE-208-1566F) Rev.8.00 Sep 07, 2005

Features

- Capable of 2.5 V gate drive
- Low drive current
- Low on-resistance $R_{DS (on)} = 1.5 \Omega$ typ. (at $V_{GS} = 4 \text{ V}$)

Outline





Channel dissipation

Channel temperature

Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	150	V
Gate to source voltage	V _{GSS}	±10	V
Drain current	ID	1	A
Drain peak current	I _{D (pulse)} Note 1	4	A
Body-drain diode reverse drain current	I _{DR}	1	A

0.9

150

-55 to +150

W

°C

°C

Storage temperature

Notes: 1. $PW \le 10 \ \mu s$, duty cycle $\le 1\%$

2. Value at Ta = $25^{\circ}C$

Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	150			V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V (BR) GSS	±10			V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μA	$V_{GS} = \pm 8 V$, $V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μA	$V_{DS} = 150 \text{ V}, \text{ V}_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	0.5	_	1.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}	_	1.5	1.95	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note 3}}$
	R _{DS (on)}	_	1.9	2.5	Ω	$I_D = 0.5 \text{ A}, V_{GS} = 2.5 \text{ V}^{Note 3}$
Forward transfer admittance	y _{fs}	0.8	1.4	_	S	$I_D = 0.5 \text{ A}, V_{DS} = 10 \text{ V}^{Note 3}$
Input capacitance	Ciss	_	98	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	31	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	14	_	pF	f = 1 MHz
Total gate charge	Qg	_	3.5	_	nC	V _{DD} = 100 V
Gate to source charge	Qgs	_	0.5	_	nC	$V_{GS} = 4 V$
Gate to drain charge	Qgd	_	1.8	_	nC	$I_D = 1 A$
Turn-on delay time	t _{d (on)}	_	8	_	ns	$V_{GS} = 4 V$
Rise time	tr	_	12	_	ns	I _D = 0.5 A
Turn-off delay time	t _{d (off)}		34		ns	$R_L = 60 \Omega$
Fall time	t _f		19		ns	
Body-drain diode forward voltage	V _{DF}	—	1.0	1.5	V	$I_F = 1 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	—	60	—	ns	$I_F = 1 \text{ A}, V_{GS} = 0$
						di _F /dt = 100 A/μs

Pch Note 2

Tch

Tstg

Note: 3. Pulse test



Main Characteristics











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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK3446TZ-E	2500 pcs	Hold box, Radial taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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